Open Hardware DSP Platform — www.ohdsp.org
CoreOne — XMOS 200 Platform
Revision 1.0

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SPDIF
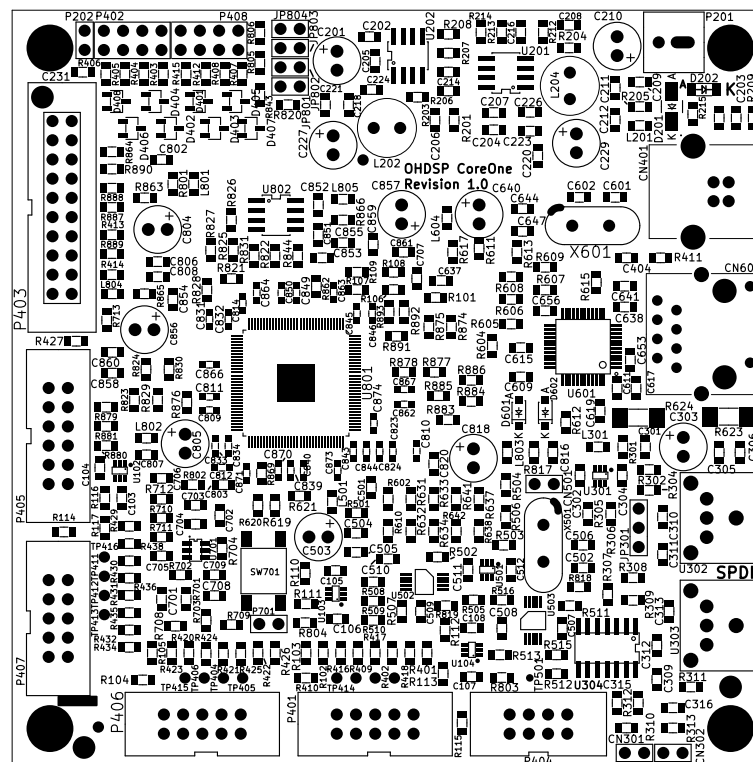
Notes:
Dirty PCB 4 layer stackup:
1oz copper
0.2mm FR4
0.5oz copper
1.2mm FR4
0.5oz copper
0.2mm FR4
1oz copper

Ethernet impedace 100ohm diff/50 ohm SE:
0.3mm trace with 0.5mm clearance between traces

50ohm traces with ground plane:
Trace 0.35mm, Clearance 0.2mm

75ohm traces with ground plane:
Trace 0.2mm, Clearance 0.3mm

89ohm traces with ground plane:
Trace 0.135mm Clearance 0.5mm to 1mm (to other traces)

Use 26AWG ribbon cables to match PCB impedances (approx 89ohm)

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Sheet:
File: DEV—CoreOne.kicad_pcb

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Size: A4	Date: 2017—02—08	Rev: **1.0**
KiCad E.D.A. kicad 4.0.5		Id: 1/1